

ABSTRACT

In FIG. 1A, A heat-dissipating device (100) for cooling of heat generated by an electrical or electronic device during operation. A numbers of heat sinks (106) are positioned in close contact with hotspot regions of the electronic device. The heat sinks (106) are coupled to a heat-conductive plate (110) so that heat is transferred away from the electrical or electronic device. The free passage of air flowing across the heat sinks (106) and the heat-conductive plate (110) provide cooling for the electrical or electronic device.